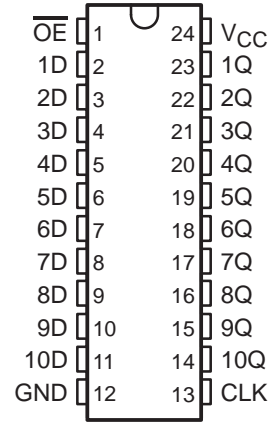


SN54ALS29821, SN74ALS29821 10-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

SDAS145B – JANUARY 1986 – REVISED JANUARY 1995

- Functionally Equivalent to AMD's AM29821
- Provide Extra Data Width Necessary for Wider Address/Data Paths or Buses With Parity
- Outputs Have Undershoot-Protection Circuitry
- Power-Up High-Impedance State
- Buffered Control Inputs Reduce dc Loading Effects
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (NT) and Ceramic (JT) 300-mil DIPs

SN54ALS29821 . . . JT PACKAGE
SN74ALS29821 . . . DW OR NT PACKAGE
(TOP VIEW)



description

These 10-bit edge-triggered D-type flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. These devices are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are true to the data (D) input.

A buffered output-enable (\overline{OE}) input can place the ten outputs in either a normal logic state (high or low logic levels) or a high-impedance state. The outputs also are in the high-impedance state during power-up and power-down conditions. The outputs remain in the high-impedance state while the device is powered down. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

\overline{OE} does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN54ALS29821 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS29821 is characterized for operation from 0°C to 70°C .

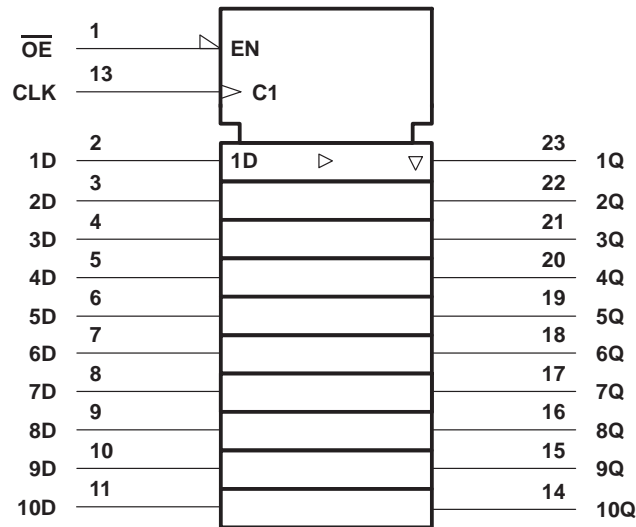
FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
\overline{OE}	CLK	D	Q
L	\uparrow	H	H
L	\uparrow	L	L
L	L	X	Q_0
H	X	X	Z

SN54ALS29821, SN74ALS29821 10-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

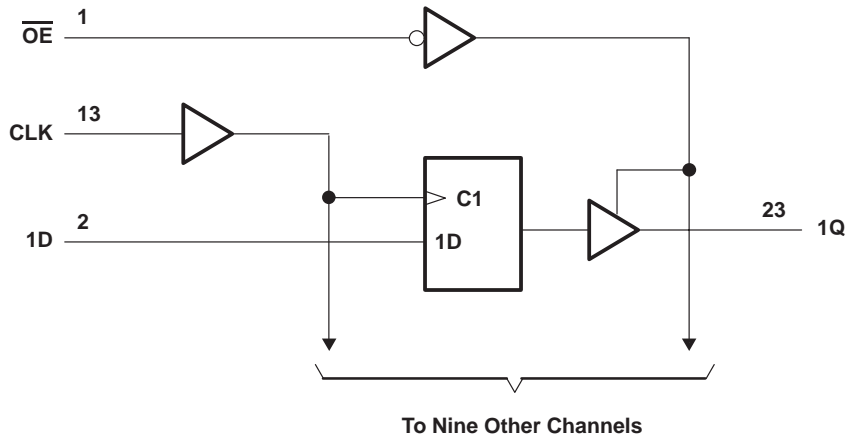
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC}	7 V
Input voltage, V_I	5.5 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T_A : SN54ALS29821	-55°C to 125°C
SN74ALS29821	0°C to 70°C
Storage temperature range	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SN54ALS29821, SN74ALS29821 10-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

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recommended operating conditions

		SN54ALS29821			SN74ALS29821			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			-24			-24	mA
I_{OL}	Low-level output current			48			48	mA
t_w	Pulse duration, CLK high or low	7			7			ns
t_{su}	Setup time, data before CLK \uparrow	4			4			ns
t_h	Hold time, data after CLK \uparrow	2			2			ns
T_A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS29821			SN74ALS29821			UNIT	
		MIN	TYP \dagger	MAX	MIN	TYP \dagger	MAX		
V_{IK}	$V_{CC} = 4.75\text{ V}$, $I_I = -18\text{ mA}$			-1.2			-1.2	V	
V_{OH}	$V_{CC} = 4.75\text{ V}$			$I_{OH} = -15\text{ mA}$	2.4	3.3	2.4	3.3	V
				$I_{OH} = -24\text{ mA}$	2	3.1	2	3.1	
V_{OL}	$V_{CC} = 4.75\text{ V}$, $I_{OL} = 48\text{ mA}$			0.35	0.5		0.35	0.5	V
I_{OZH}	$V_{CC} = 5.25\text{ V}$, $V_O = 2.4\text{ V}$			50			20	μA	
I_{OZL}	$V_{CC} = 5.25\text{ V}$, $V_O = 0.4\text{ V}$			-50			-20	μA	
I_I	$V_{CC} = 5.25\text{ V}$, $V_I = 5.5\text{ V}$			0.1			0.1	mA	
I_{IH}	$V_{CC} = 5.25\text{ V}$, $V_I = 2.7\text{ V}$			20			20	μA	
I_{IL}	$V_{CC} = 5.25\text{ V}$, $V_I = 0.4\text{ V}$			-0.5			-0.2	mA	
$I_{OS}\ddagger$	$V_{CC} = 5.25\text{ V}$, $V_O = 0$	-75		-250	-75		-250	mA	
I_{CC}	$V_{CC} = 5.25\text{ V}$, Outputs open		80	115		80	115	mA	

\dagger All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

\ddagger Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

SN54ALS29821, SN74ALS29821
10-BIT BUS-INTERFACE FLIP-FLOPS
WITH 3-STATE OUTPUTS

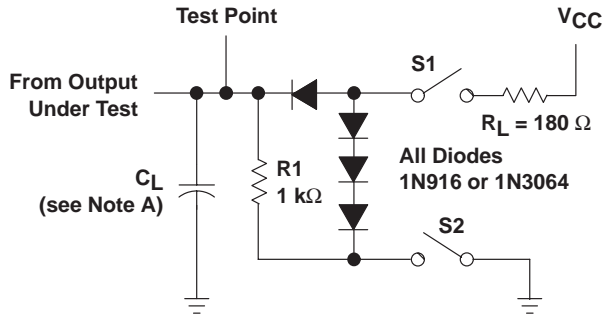
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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	$V_{CC} = \text{MIN to MAX}^\dagger$, $T_A = \text{MIN to MAX}^\dagger$				UNIT
				SN54ALS29821		SN74ALS29821		
				MIN	MAX	MIN	MAX	
t_{PLH}	CLK	Any Q	$C_L = 50 \text{ pF}$	2	11.5	2	10	ns
t_{PHL}				2	11.5	2	10	
t_{PLH}	CLK	Any Q	$C_L = 300 \text{ pF}$	2	21		16	ns
t_{PHL}				2	21		16	
t_{PZH}	\overline{OE}	Any Q	$C_L = 50 \text{ pF}$	1	17		14	ns
t_{PZL}				1	17		14	
t_{PZH}	\overline{OE}	Any Q	$C_L = 300 \text{ pF}$	1	25		20	ns
t_{PZL}				1	29.5		23	
t_{PHZ}	\overline{OE}	Any Q	$C_L = 50 \text{ pF}$	1	16		14	ns
t_{PLZ}				1	14		12	
t_{PHZ}	\overline{OE}	Any Q	$C_L = 5 \text{ pF}$	1	12		9	ns
t_{PLZ}				1	11		9	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

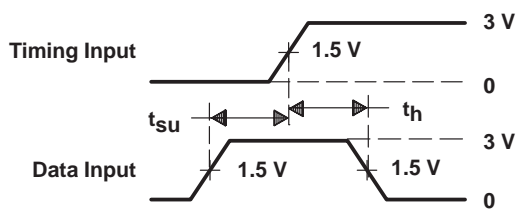
PARAMETER MEASUREMENT INFORMATION



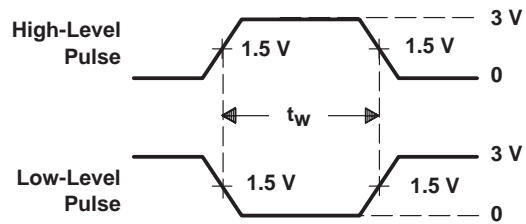
LOAD CIRCUIT

SWITCH POSITION TABLE

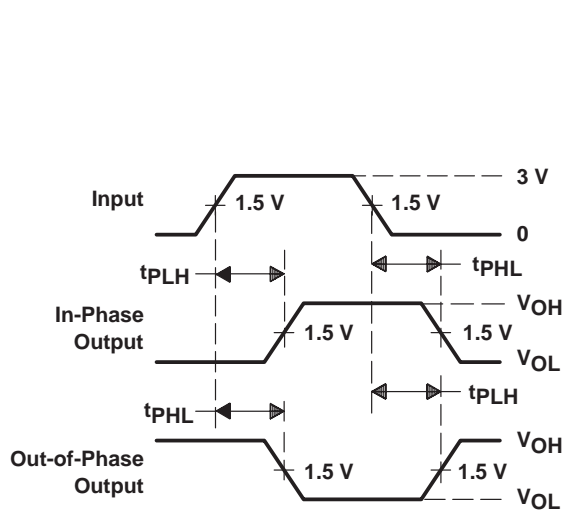
TEST	S1	S2
t_{PLH}	Closed	Closed
t_{PHL}	Closed	Closed
t_{PZH}	Open	Closed
t_{PZL}	Closed	Open
t_{PHZ}	Closed	Closed
t_{PLZ}	Closed	Closed



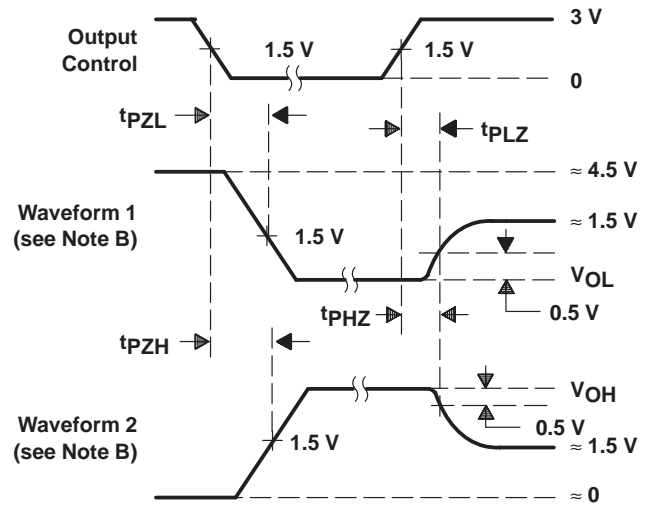
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATIONS



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9061601LA	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ALS29821DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29821DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29821DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29821DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29821DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29821NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS29821NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54ALS29821JT	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS29821DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



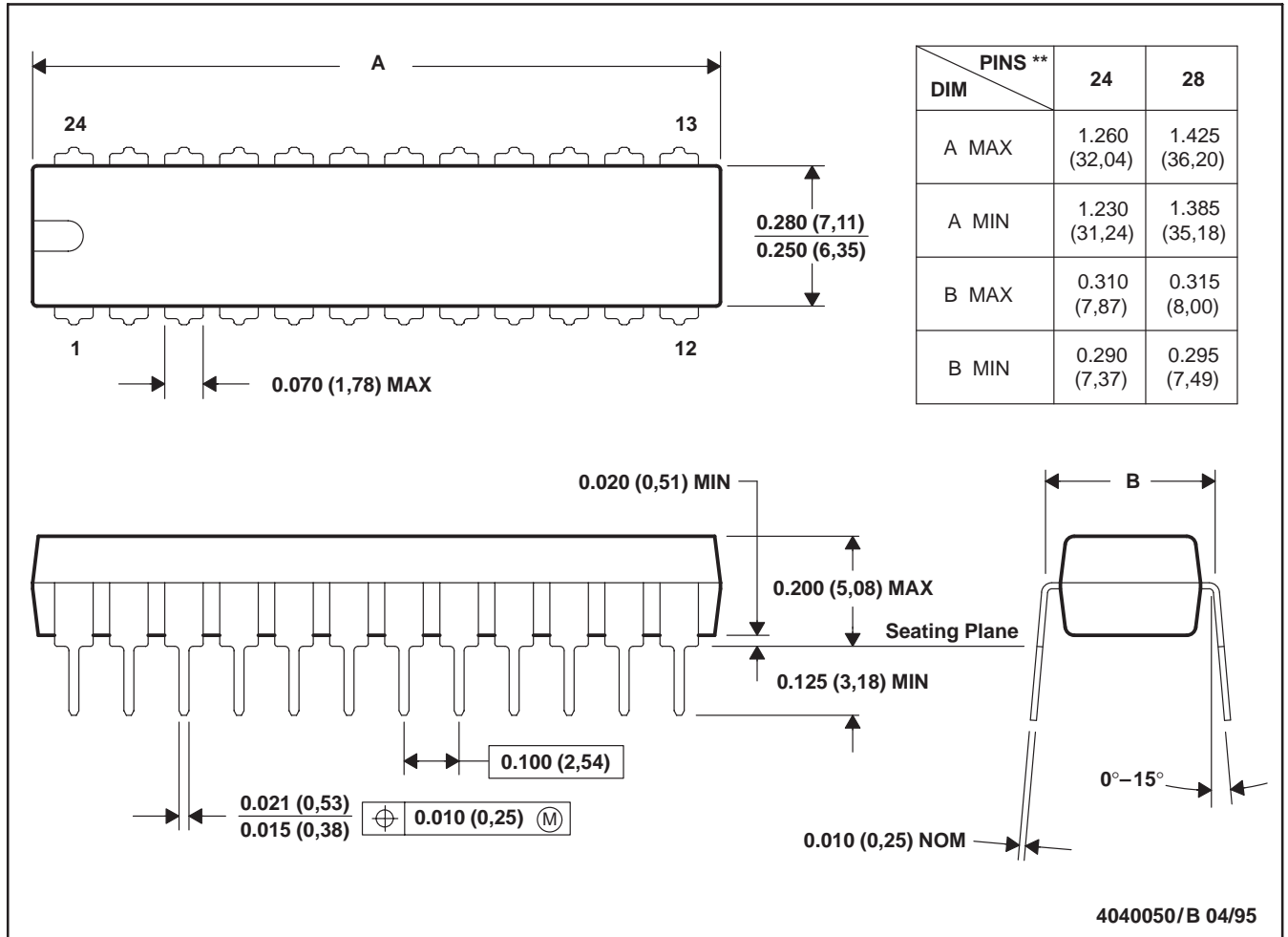
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS29821DWR	SOIC	DW	24	2000	346.0	346.0	41.0

NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

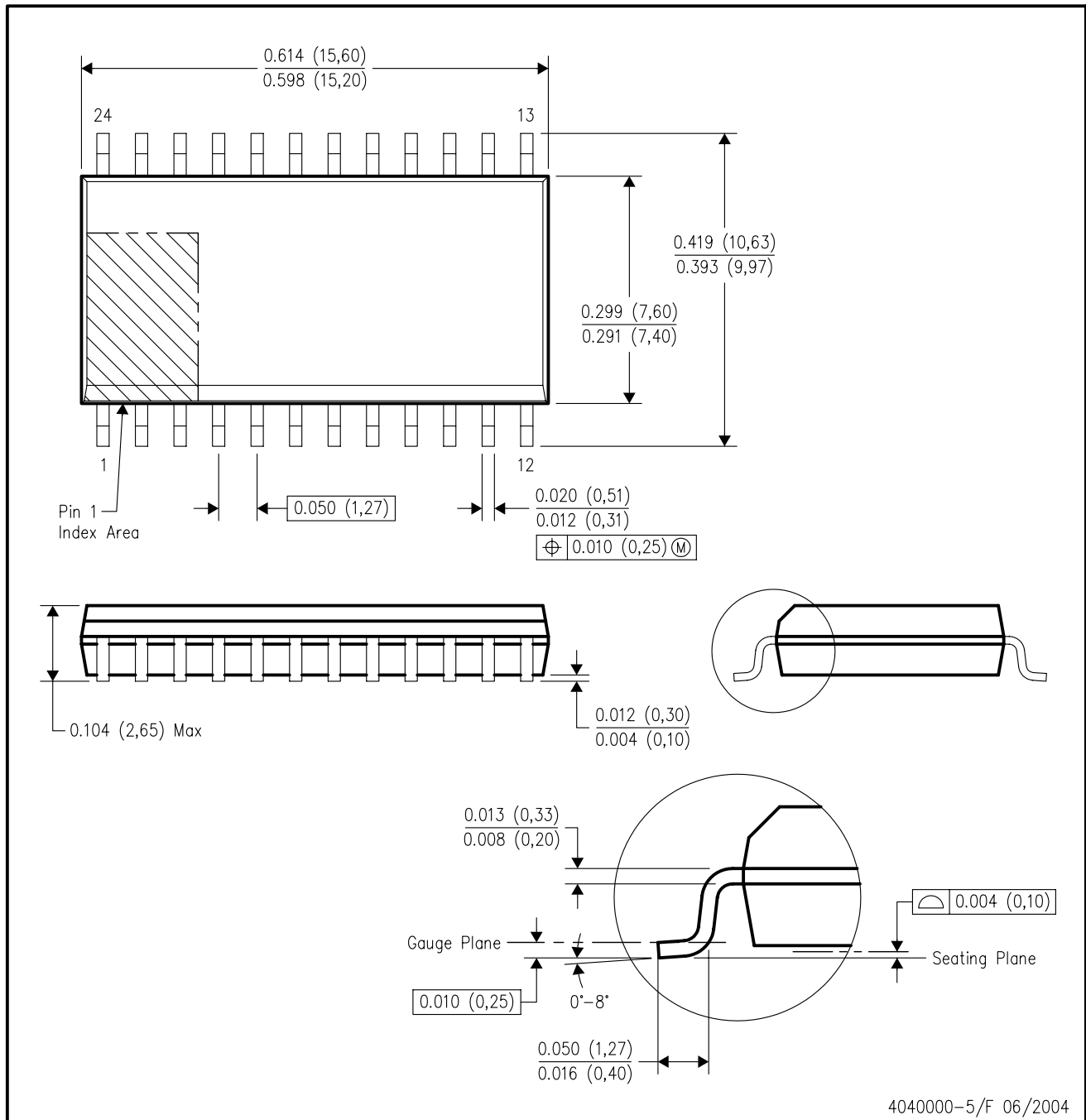
24 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AD.

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

24 LEADS SHOWN



4040110/C 08/96

- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

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